

CLAIMS

1. A positive photosensitive resin composition comprising an alkali-soluble resin, a 1,2-quinone diazide compound, a crosslinking compound having at least two 5 epoxy groups and a surfactant, wherein the above alkali-soluble resin is a copolymer comprising a carboxyl group-containing acrylic monomer, a hydroxyl group-containing acrylic monomer and an N-substituted maleimide as essential components.
- 10 2. The positive photosensitive resin composition according to Claim 1, which comprises the 1,2-quinone diazide compound in an amount of from 5 to 100 parts by weight, the crosslinking compound having at least two epoxy groups in an amount of from 1 to 50 parts by weight, and the surfactant in an amount of from 0.01 to 2 15 parts by weight, based on 100 parts by weight of the alkali-soluble resin component.
3. The positive photosensitive resin composition according to Claim 1 or 2, wherein the number average 20 molecular weight of the copolymer is from 2,000 to 9,000.
4. The positive photosensitive resin composition according to any one of 1 to 3, wherein the copolymer comprises the carboxyl group-containing acrylic monomer in an amount of from 5 to 30 mol%, the hydroxyl group-containing acrylic monomer in an amount of from 5 to 50 25 mol% and the N-substituted maleimide in an amount of from 10 to 70 mol% as monomer components.

5. The positive photosensitive resin composition according to any one of Claims 1 to 4, wherein the surfactant is a fluorine type surfactant.
6. A method for forming a pattern, which uses the
5 positive photosensitive resin composition as defined in any one of Claims 1 to 5 wherein the postbake conditions are changed to arbitrarily form a pattern having a semicircular or trapezoidal section.